

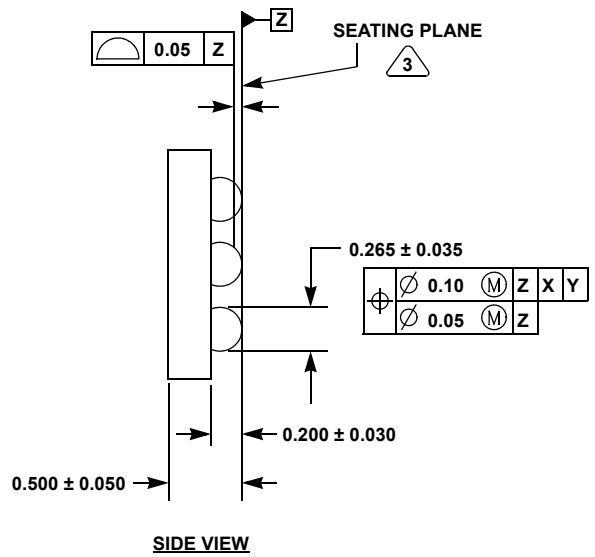
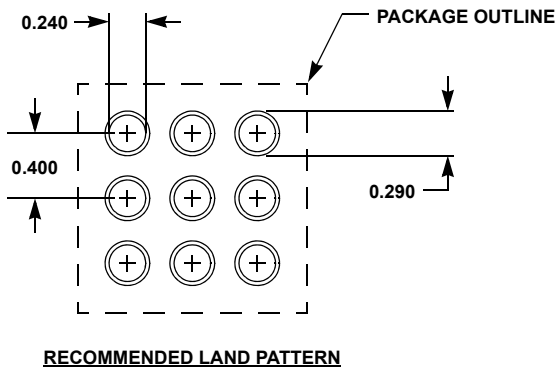
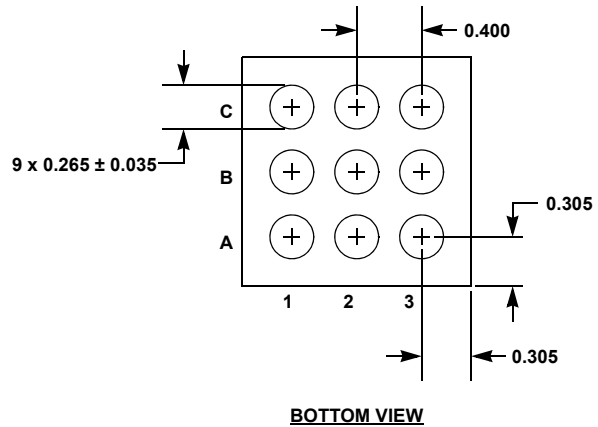
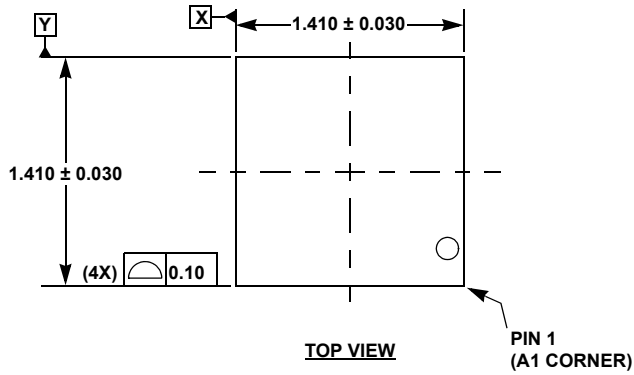
Plastic Packages for Integrated Circuits

Package Outline Drawing

W3x3.9E

3x3 ARRAY 9 BALLS WITH 0.40 PITCH WAFER LEVEL CHIP SCALE PACKAGE

Rev 0, 8/14



NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerance per ASMEY 14.5 - 1994, and JESD 95-1 SPP-010.
3. NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).